

## Foreword

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An area of growing importance in microelectronics is clearly Asia. As a result, it is my pleasure to introduce to you our newest associate editor, Dr. Yanhong Tian from Harbin Institute of Technology in Harbin, China.

Dr. Tian currently serves as an Associate Professor at the Harbin Institute of Technology. She received her Ph.D. Degree in Materials Science and Engineering from Harbin Institute of Technology in 2003, and worked at the University of Waterloo, Canada, as a postdoctoral fellow in the Department of Mechanical Engineering from 2004-2005. Her current research interests are advanced microjoining technologies in electronic packaging and assembly, including wire bonding, laser soldering, lead free soldering, reliability analysis and finite element modeling. Until 2008, she has published more than 40 papers and contributed

one chapter in the book named “Microjoining and Nanojoining” published at Woodheads Published Ltd. One of her papers has been awarded “Emerald Highly Commended Paper” at 2004, and two papers have been awarded Best Paper at International Conference on Electronic Packaging Technology 2005 and 2008, respectively. She currently serves as an associate director of Welding Society Committee in the China Institute of Electronics.

Her strong background and active research efforts in microelectronics will be a great asset for the Journal, and it is a privilege to be able to work with her on this publication.

Fred D. Barlow III, Ph.D.  
Editor-in-Chief